

WAP321015-NCSC2

Dual Wavelength SMD Type Emitter

Features

- Side view 1204 package
- Viewing Angle = $\pm 65^{\circ}$
- Compatible with infrared and vapor phase reflow solder process
- High reliability
- RoHS compliance

Applications

- Optical indicator.
- Switch and Symbol Display.

Description

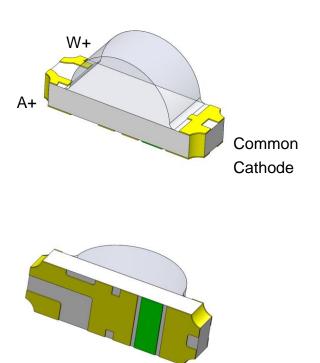
The WAP321015-NCSC2 is a double LED housed in a miniature SMD package. The device has a White and Amber LED.

Static electricity and surge damage the LEDs.

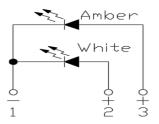
It is recommended to use a wrist band or

anti-electrostatic glove when handling the LEDs.

Package Outline



Schematic





Absolute Maximum Rating at 25°C

Symbol	Parameters		Ratings	Units	Notes
1_	Continuous Forward Current	W	25	٣A	
I _F	Continuous Forward Current	А	25	mA	
1	Deek Ferward Current	W	60		1
IFP Peak Forward Current		А	60	mA	
V _R	Reverse Voltage	5	V		
Topr	T _{opr} Operating Temperature		-40 ~ +85	0C	
T _{stg}	T _{stg} Storage Temperature		-40 ~ +100	0 C	
T _{sol} Soldering Temperature			260	0 C	2
Р	Power Dissipation at(or below) 25°C Free Air		95		
P _D Temperature		А	60	mW	

Electro-Optical Characteristics TA = 25°C (unless otherwise specified)

Optical Characteristics (White)

Symbol	Parameters	Test Conditions	Min	Тур	Max	Units	Notes
lv	Luminous Intensity	l⊧=5mA	112	-	285	mcd	3
λD	Dominant Wavelength	I⊧=5mA	-	-	-	nm	4
θ1/2	Angle of Half Intensity	I⊧=5mA	-	±65	-	deg	

Electrical Characteristics

Symbol	Parameters	Test Conditions	Min	Тур	Max	Units	Notes
VF	Forward Voltage	I⊧=5mA	2.6	-	3.2	V	
I _R	Reverse Current	V _R =5V	-	-	1	μA	



Optical Characteristics (Amber)

Symbol	Parameters	Test Conditions	Min	Тур	Max	Units	Notes
lv	Luminous Intensity	I⊧=5mA	18	-	45	mcd	3
λd	Dominant Wavelength	I⊧=5mA	600	605	610	nm	4
θ1/2	Angle of Half Intensity	I⊧=5mA	-	±65	-	deg	

Electrical Characteristics

Symbol	Parameters	Test Conditions	Min	Тур	Max	Units	Notes
VF	Forward Voltage	I⊧=5mA	1.6	-	2.2	V	
IR	Reverse Current	V _R =5V	-	-	1	μA	

Notes:

- 1. I_{FP} Conditions--Pulse Width $\leq 100\mu s$ and Duty $\leq 10\%$.
- 2. Soldering time ≤ 10 seconds.
- 3. Bin Range of Luminous Intensity

White						
Bin Code	Min	Max	Unit	Condition		
R	112	180	mcd			
S	180	285	mea	I _F =5mA		
		Amber				
Bin Code	Min	Max	Unit	Condition		
М	18.0	28.5	med	I _F =5mA		
N	28.5	45.0	mcd	IF=SIIIA		

Tolerance of: Luminous Intensity $\pm 10\%$



WAP321015-NCSC2

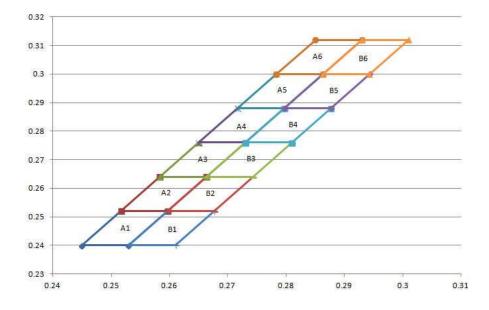
Dual Wavelength SMD Type Emitter

Bin Code	CIE_x	CIE_y	Bin Code	CIE_x	CIE_y
	0.2450	0.2400		0.2530	0.2400
A 1	0.2517	0.2520	B1	0.2597	0.2520
A1	0.2597	0.2520	ы	0.2677	0.2520
	0.2530	0.2400		0.2610	0.2400
	0.2517	0.2520		0.2597	0.2520
A2	0.2583	0.2640	B2	0.2663	0.2640
AZ.	0.2663	0.2640	DZ	0.2743	0.2640
	0.2597	0.2520		0.2677	0.2520
	0.2583	0.2640		0.2663	0.2640
A3	0.2650	0.2760	В3	0.2730	0.2760
AS	0.2730	0.2760	5	0.2810	0.2760
	0.2663	0.2640		0.2743	0.2640
	0.2650	0.2760		0.2730	0.2760
A4	0.2717	0.2880	B4	0.2797	0.2880
~+	0.2797	0.2880	04	0.2877	0.2880
	0.2730	0.2760		0.2810	0.2760
	0.2717	0.2880		0.2797	0.2880
A5	0.2783	0.3000	B5	0.2863	0.3000
AJ	0.2863	0.3000	60	0.2943	0.3000
	0.2797	0.2880		0.2877	0.2880
	0.2783	0.3000		0.2863	0.3000
A6	0.2850	0.3120	B6	0.2930	0.3120
A0	0.2930	0.3120	00	0.3009	0.3120
	0.2863	0.3000		0.2877	0.2880

Bin Range of Chromaticity Coordinates 4.



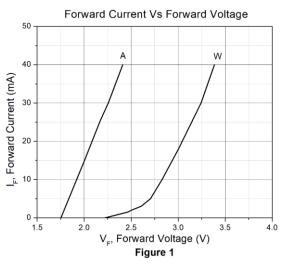
WAP321015-NCSC2 Dual Wavelength SMD Type Emitter



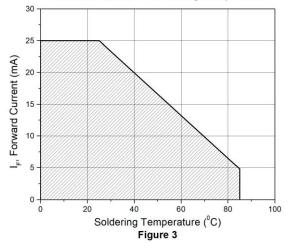


WAP321015-NCSC2 Dual Wavelength SMD Type Emitter

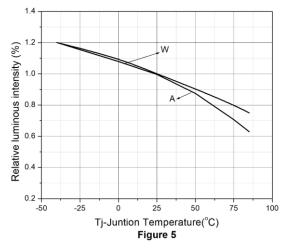
Typical Characteristic Curves

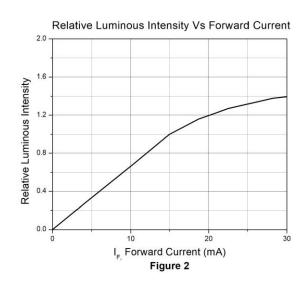


Forward Current Vs Soldering Temperature



Relative Luminous Intensity Vs Juntion Temperature





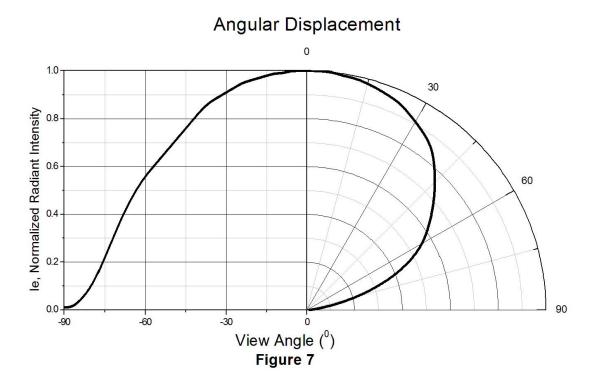
Forword Voltage Shift Vs Juntion Temperature 0.20 0.15 0.10 Forword Voltage Shift -V 0.05 0.00 -0.05 -0.10 -0.15 -0.20 -25 0 50 75 -50 25 100 Tj-Juntion Temperature (°C) Figure 4 Radiant Intensity Vs Wavelength 1.0 W Α I., Normalized Radiant Intensity (%) 0.8 0.6 0.4 0.2 0.0 400 450 500 550 600 650 700 750 800 850

 λ , Wavelength (nm)

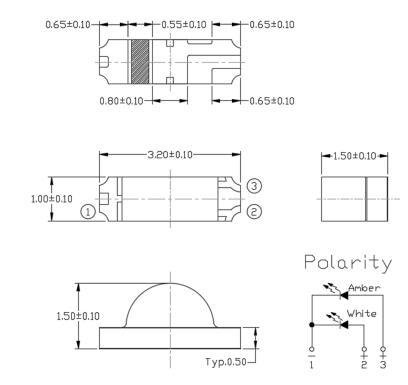
Figure 6



Typical Characteristic Curves



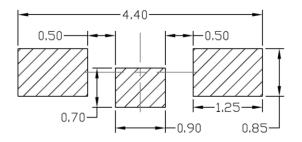




Package Dimension All dimensions are in mm, unless otherwise stated

Note: Tolerance unless mentioned is ± 0.1 mm.

Recommended Soldering Mask All dimensions are in mm, unless otherwise stated



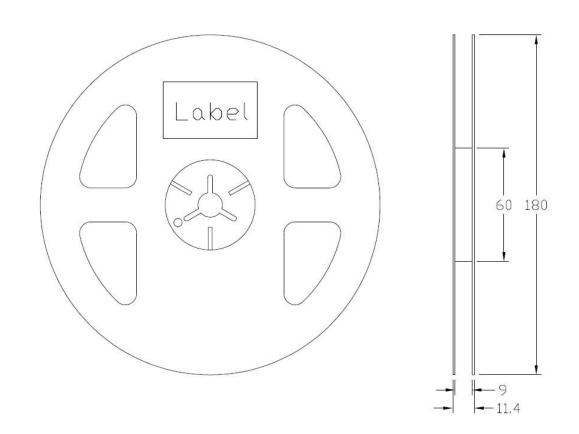
Note: Tolerance unless mentioned is ±0.1mm.

Ordering Information

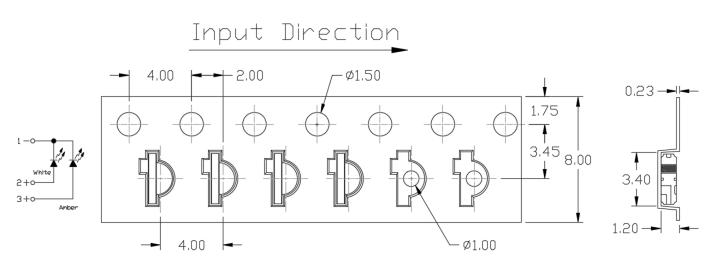
Part Number	Description	Quantity
WAP321015-NCSC2	Tape & Reel	2000 pcs



Reel Dimension All dimensions are in mm, unless otherwise stated



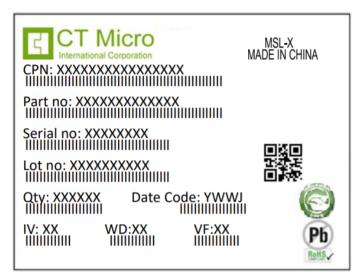
Tape Dimension All dimensions are in mm, unless otherwise stated



Note: Tolerance unless mentioned is ±0.1mm.



Label Form Specification



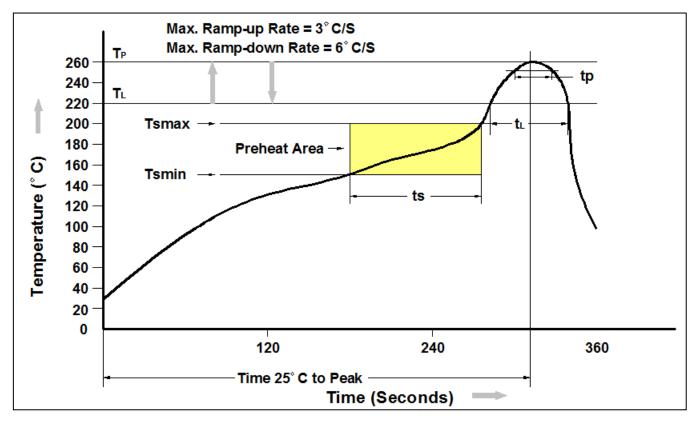
CPN : Customer Part Number Part no: CTM Production Number Serial no: Production Number Lot no: Lot number Q'ty: Packing Quantity Date Code: Manufacture Date IV : Bin Code of Luminous Intensity WD : Bin Code of Dominant Wavelength VF : Bin Code of Forward Voltage MADE IN CHINA: Production Place

Storage Condition

- 1. Do not open moisture proof bag before the products are ready to use.
- 2. The moisture barrier bag should be stored at 30°C and 90%R.H. max. before opening. Shelf life of non-opened bag is 12 months after the bag sealing date.
- 3. After opening the moisture barrier bag floor life is 1 year at 30°C/60%RH. max. Unused LEDs should be resealed into moisture barrier bag. (Refer to J-STD-020 Standard)
- 4. If the moisture absorbent material has faded away or the LEDs have exceeded the storage time, baking treatment should be performed using the J-STD-033 Standard conditions.



Reflow Profile



Profile Feature	Pb-Free Assembly Profile
Temperature Min. (Tsmin)	150°C
Temperature Max. (Tsmax)	200°C
Time (ts) from (Tsmin to Tsmax)	60-120 seconds
Ramp-up Rate (t∟ to t⊳)	3°C/second max.
Liquidous Temperature (T∟)	217°C
Time (t _L) Maintained Above (T _L)	60 – 150 seconds
Peak Body Package Temperature	260°C +0°C / -5°C
Time (t _P) within 5°C of 260°C	30 seconds
Ramp-down Rate (T_P to T_L)	6°C/second max
Time 25°C to Peak Temperature	8 minutes max.



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